SDAS228A - JUNE 1982 - REVISED JANUARY 1995

- Compare Two 8-Bit Words
- Totem-Pole Outputs $(\overline{P} = \overline{Q})$
- 'ALS688 Are Identical to 'ALS521
- Package Options Include Plastic Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

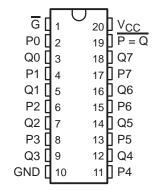
These identity comparators perform comparisons on two 8-bit binary or BCD words and provide $\overline{P} = \overline{Q}$ outputs. These devices have totem-pole outputs.

The SN54ALS688 is characterized for operation over the full military temperature range of -55° C to 125°C. The SN74ALS688 is characterized for operation from 0°C to 70°C.

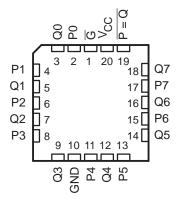
FUNCTION TABLE

IN	PUTS	OUTDUT
DATA P, Q	ENABLE G	OUTPUT P = Q
P = Q	L	L
P > Q	L	Н
P < Q	L	Н
X	Н	Н

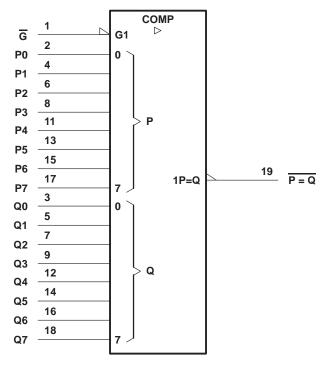
SN54ALS688 . . . J PACKAGE SN74ALS688 . . . DW OR N PACKAGE (TOP VIEW)



SN54ALS688 . . . FK PACKAGE (TOP VIEW)



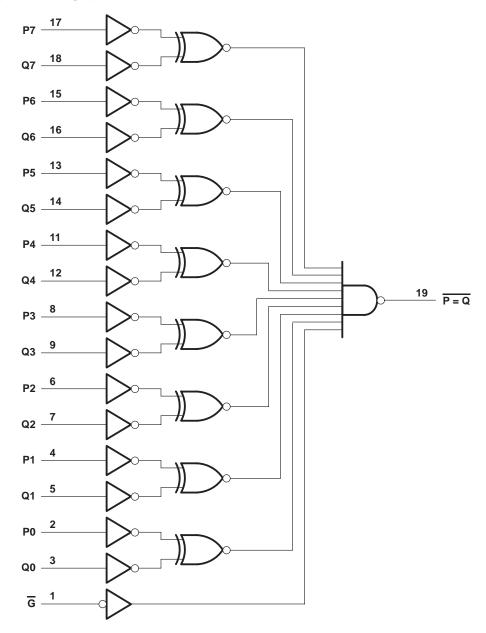
logic symbol†



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.



logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Operating free-air temperature range, T _A : SN54ALS688	–55°C to 125°C
SN74ALS688	0°C to 70°C
Storage temperature range	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



SN54ALS688, SN74ALS688 **8-BIT IDENTITY COMPARATORS**

SDAS228A - JUNE 1982 - REVISED JANUARY 1995

recommended operating conditions

		SN	54ALS6	88	SN74ALS688			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vсс	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.7			0.8	V
IOH	High-level output current			-1			-2.6	mA
loL	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST OF	TEST CONDITIONS			88	SN	74ALS6	88	LINUT
PARAMETER	IEST CC	TEST CONDITIONS				MIN	TYP [†]	MAX	UNIT
VIK	V _{CC} = 4.5 V,	$I_{I} = -18 \text{ mA}$			-1.5			-1.5	V
	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		V _{CC} -2	2		
Voн	V _{CC} = 4.5 V	$I_{OH} = -1 \text{ mA}$	2.4	3.3					V
	VCC = 4.5 V	$I_{OH} = -2.6 \text{ mA}$				2.4	3.3		
VOL	V _{CC} = 4.5 V	$I_{OL} = 12 \text{ mA}$		0.25	0.4		0.25	0.4	V
VOL.	VCC = 4.5 V	$I_{OL} = 24 \text{ mA}$					0.35	0.5	V
lį	$V_{CC} = 5.5 \text{ V},$	V _I = 7 V			0.1			0.1	mA
lН	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
I _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			-0.1			-0.1	mA
I _O ‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
Icc	$V_{CC} = 5.5 \text{ V},$	See Note 1		12	19		12	19	mA

switching characteristics (see Figure 1)

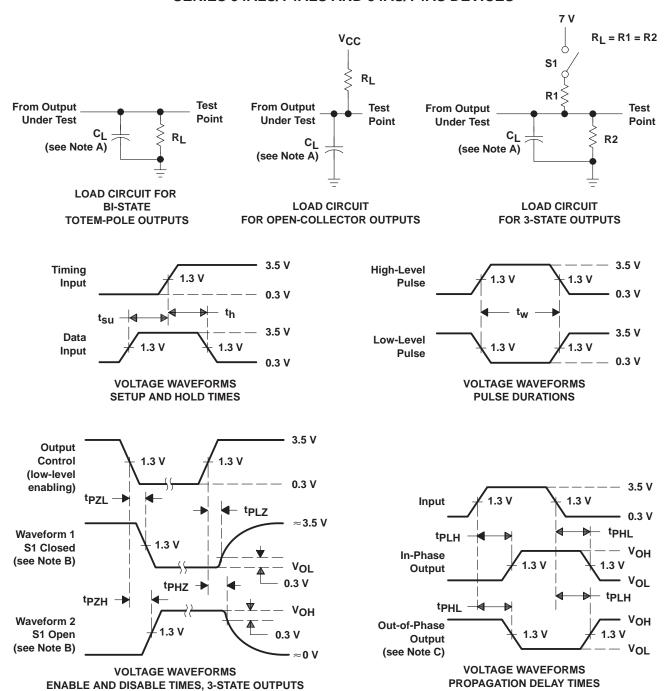
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C C _L R _L T _A	UNIT			
			SN54A	LS688	SN74A	LS688	
			MIN	MAX	MIN	MAX	
^t PLH	Р	$\overline{P} = Q$	3	16	3	12	ns
^t PHL	P	P=Q	5	25	5	20	115
^t PLH	0	$\overline{P} = Q$	3	16	3	12	20
^t PHL	Q	P = Q	5	25	5	20	ns
t _{PLH}	G	$\overline{P} = Q$	3	15	3	12	ns
t _{PHL}	G	Γ≡Q	5	25	5	22	115

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



[†] All typical values are at $V_{CC} = 5$ V, $T_A = 25^{\circ}$ C. ‡ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{CC} . NOTE 1: I_{CC} is measured with \overline{G} grounded, P and Q at 4.5 V.

PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- D. All input pulses have the following characteristics: PRR \leq 1 MHz, t_{Γ} = t_{f} = 2 ns, duty cycle = 50%.
- E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms



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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-88578012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 88578012A SNJ54ALS 688FK
5962-8857801RA	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8857801RA SNJ54ALS688J
5962-8857801SA	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8857801SA SNJ54ALS688W
SN54ALS688J	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54ALS688J
SN54ALS688J.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54ALS688J
SN74ALS688DW	Obsolete	Production	SOIC (DW) 20	-	-	Call TI	Call TI	0 to 70	ALS688
SN74ALS688DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS688
SN74ALS688DWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS688
SN74ALS688N	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74ALS688N
SN74ALS688N.A	Active	Production	PDIP (N) 20	20 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	SN74ALS688N
SN74ALS688NSR	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS688
SN74ALS688NSR.A	Active	Production	SOP (NS) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS688
SN74ALS688NSR.B	Active	Production	SOP (NS) 20	2000 LARGE T&R	-	NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS688
SNJ54ALS688FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 88578012A SNJ54ALS 688FK
SNJ54ALS688FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 88578012A SNJ54ALS 688FK
SNJ54ALS688J	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8857801RA SNJ54ALS688J
SNJ54ALS688J.A	Active	Production	CDIP (J) 20	20 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8857801RA SNJ54ALS688J
SNJ54ALS688W	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8857801SA SNJ54ALS688W



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Orderable part number	Status (1)	Material type	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
SNJ54ALS688W.A	Active	Production	CFP (W) 20	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-8857801SA SNJ54ALS688W

⁽¹⁾ Status: For more details on status, see our product life cycle.

- (3) RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.
- (4) Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.
- (5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.
- (6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF SN54ALS688, SN74ALS688:

Catalog: SN74ALS688

Military: SN54ALS688

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not vet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.



PACKAGE OPTION ADDENDUM

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NOTE: Qualified Version Definitions:

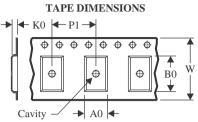
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS688DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ALS688NSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS688DWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74ALS688NSR	SOP	NS	20	2000	356.0	356.0	45.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-88578012A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-8857801SA	W	CFP	20	25	506.98	26.16	6220	NA
SN74ALS688N	N	PDIP	20	20	506	13.97	11230	4.32
SN74ALS688N.A	N	PDIP	20	20	506	13.97	11230	4.32
SNJ54ALS688FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ALS688FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ALS688W	W	CFP	20	25	506.98	26.16	6220	NA
SNJ54ALS688W.A	W	CFP	20	25	506.98	26.16	6220	NA

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.

 D. Index point is provided on cap for terminal identification only.

 E. Falls within Mil—Std 1835 GDFP2—F20



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.





SOIC



- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



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